

FEATURES

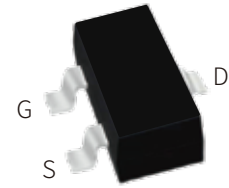
Ultra low on-resistance: $V_{DS}=30V, R_{DS(ON)} \leq 52m\Omega$

@ $V_{GS}=10V, I_D=4.2A$

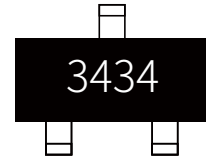
For PWM application

For Load switch application

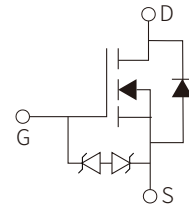
Surface Mount device



SOT-23



Marking



Schematic Symbol

APPLICATION

Case: SOT-23

Case Material: Molded Plastic. UL flammability

Classification Rating: 94V-0

APPROVALS

RoHS Compliance with 2011/65/EU

HF Compliance with IEC61249-2-21:2003

ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Drain Current-Continuous	I_D	3.5	A
Drain Current-Continuous	I_D	2.8	A
Pulsed Drain Voltage	I_{DM}	30	A
Gate-Source Voltage	V_{GS}	± 20	V
Total Power Dissipation	P_D	1.0	W
Total Power Dissipation	P_D	0.64	W
Thermal resistance from Junction to ambient	$R_{\theta JA}$	125	$^\circ\text{C}/\text{W}$
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS(T_a=25°C)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-source Breakdown Voltage*	BV _{DSS}	V _{GS} =0V, I _D =250μA	30			V
Zero Gate Voltage Drain Current*	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	μA
Gate-Body Leakage*	I _{GSS}	V _{GS} =±16V, V _{DS} =0V			±10	uA
Gate Threshold Voltage*	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.32	1.8	V
Static Drain-Source On-Resistance*	R _{DS(on)}	V _{GS} =10V, I _D =4.2A		43	52	mΩ
		V _{GS} =10V, I _D =4.2A, T _J =125°C		58	74	
		V _{GS} =4.5V, I _D =2A		59	75	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =4.2A		8.5		S
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, f=1MHz		1	1.5	Ω
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1.0MHz		269	340	pF
Output Capacitance	C _{oss}			65		
Reverse Transfer Capacitance	C _{rss}			41		
Turn-On Delay Time	t _{d(on)}	V _{GS} =10V, R _L =3.6Ω V _{DS} =15V, R _{GEN} =3Ω		2.6	3.8	ns
Turn-On Rise Time	t _r			5.5	8	
Turn-Off Delay Time	t _{d(off)}			15.2	23	
Turn-Off Fall Time	t _f			3.7	5.5	
Diode forward voltage	V _{SD}	I _S =1A, V _{GS} =0V		0.77	1	V
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =4.2A		5.7	7.2	nC
Gate Source Charge	Q _{gs}			1.37		
Gate Drain Charge	Q _{gd}			0.65		
Diode forward current	I _S				1.8	A
Body Diode Reverse Recovery Time	t _{rr}	I _F =4.2A, di/dt=100A/us		15.5	21	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F =4.2A, di/dt=100A/us		7.1		nC

*Pulse test ; Pulse width ≤300μs, Duty cycle ≤ 0.5%

PARAMETER CHARACTERISTIC CURVE

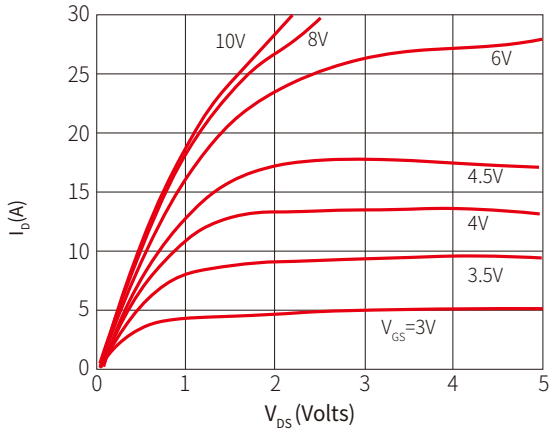
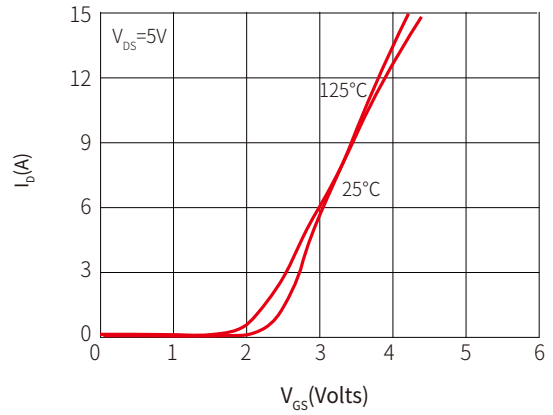
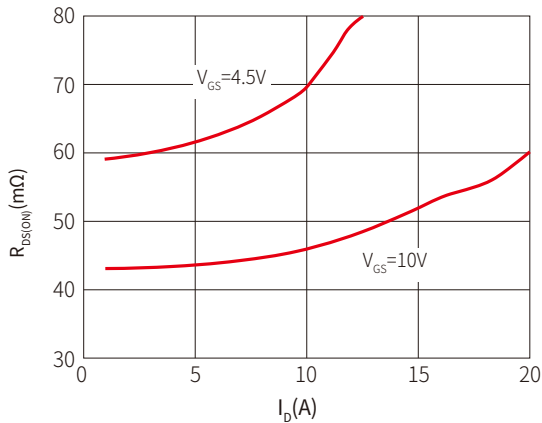
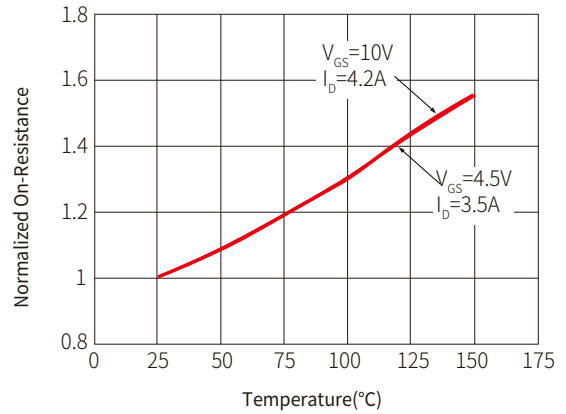
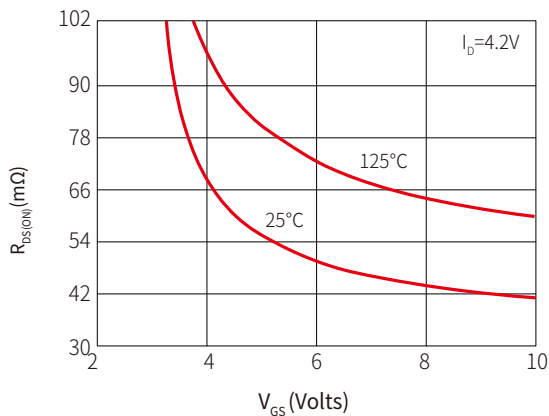
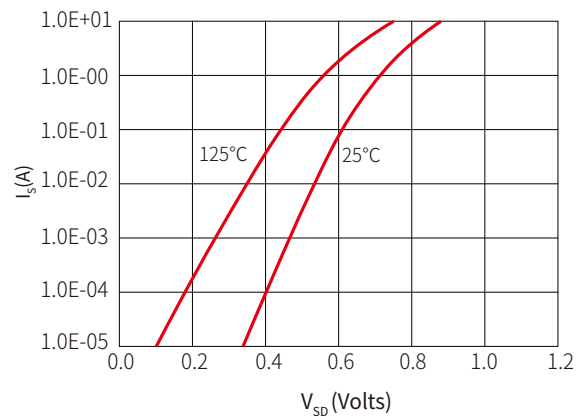
Fig 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics


Figure 7: Gate-Charge Characteristics

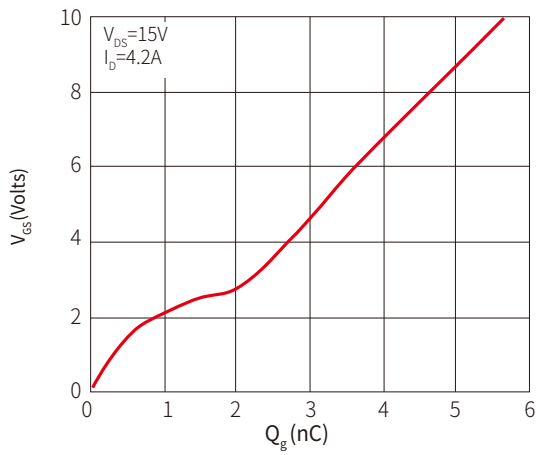


Figure 8: Capacitance Characteristics

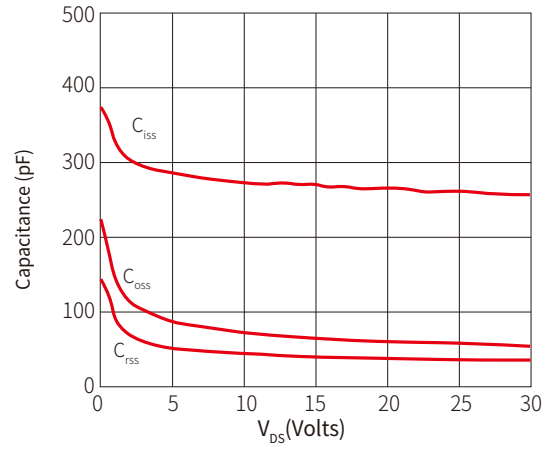


Figure 9: Maximum Forward Biased Safe Operating Area

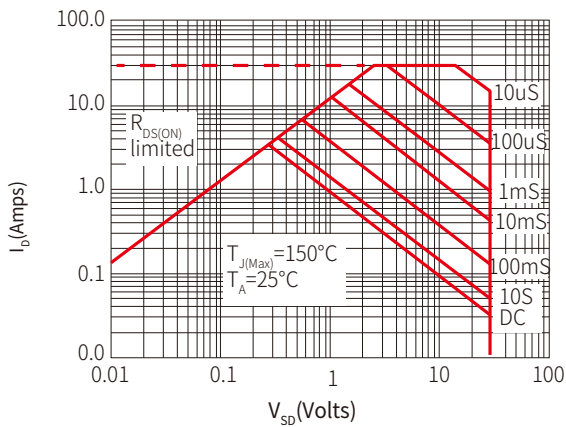


Figure 10: Single Pulse Power Rating Junction-to-Ambient

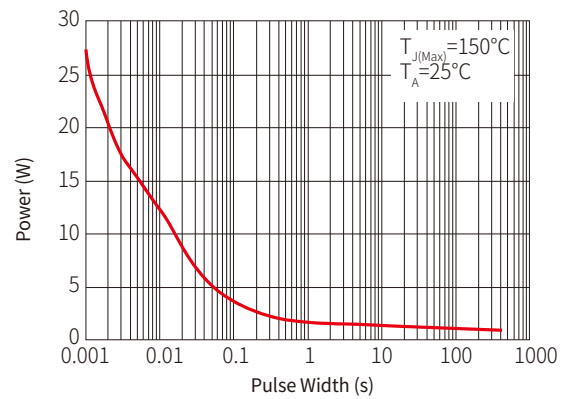
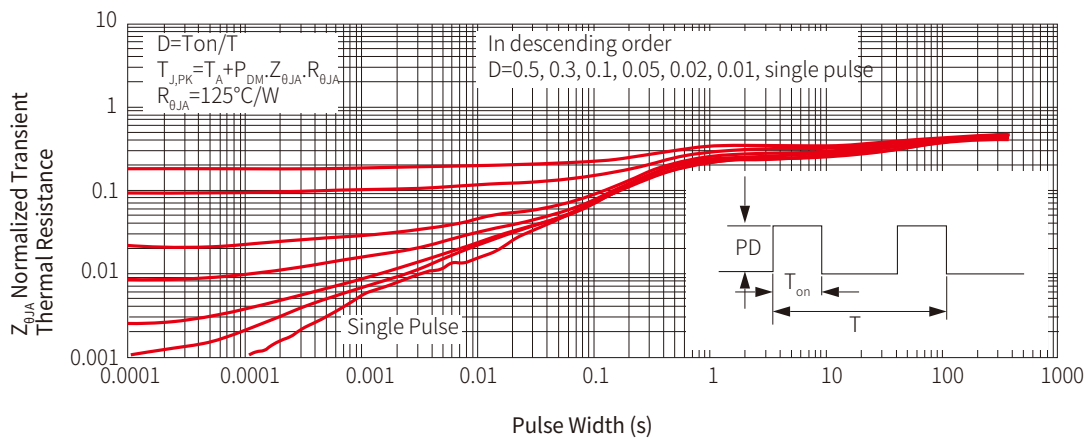
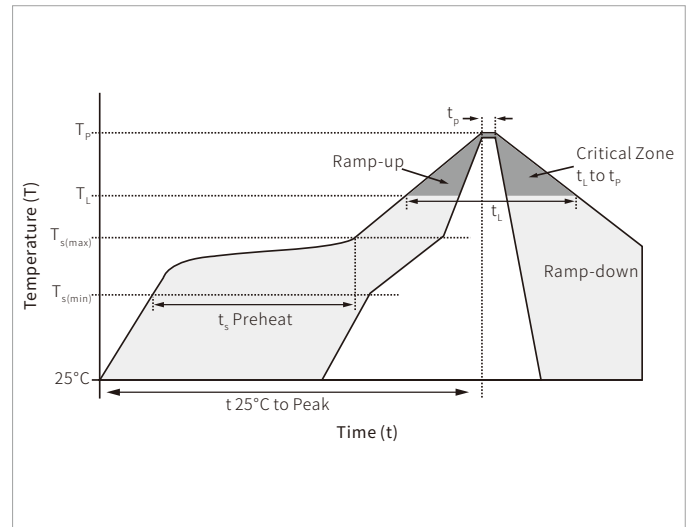


Figure 11: Normalized Maximum Transient Thermal Impedance

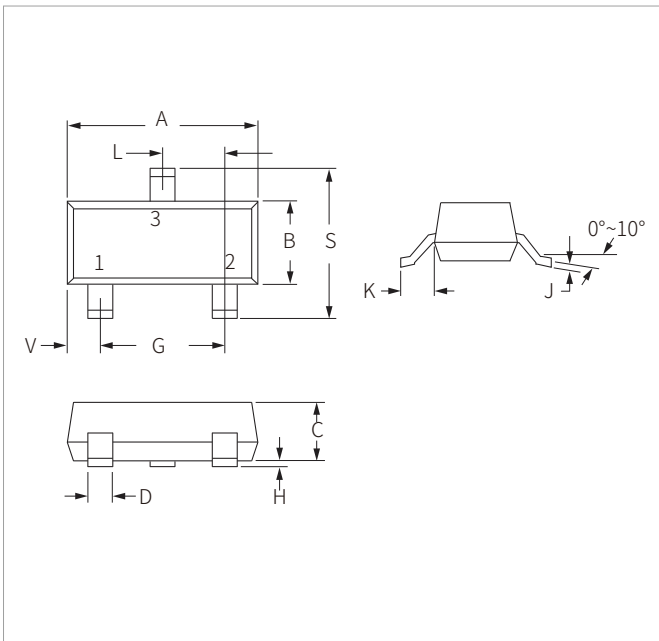


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

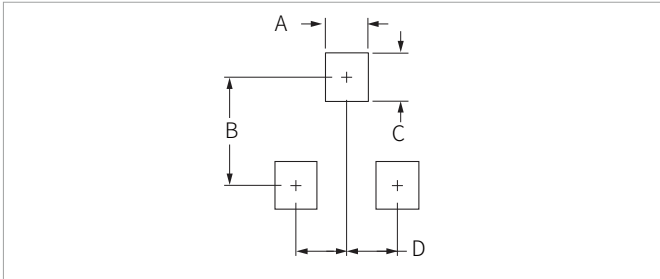


SOT-23 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.05	0.110	0.120
B	1.20	1.40	0.047	0.055
C	0.90	1.15	0.035	0.045
D	0.37	0.50	0.015	0.020
G	1.75	2.05	0.069	0.081
H	0.01	0.100	0.001	0.004
J	0.085	0.180	0.003	0.007
K	0.35	0.69	0.014	0.029
L	0.89	1.02	0.035	0.040
S	2.10	2.65	0.083	0.104
V	0.45	0.60	0.018	0.024

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.71	0.97	0.028	0.038
B	1.88	2.13	0.074	0.084
C	0.71	0.97	0.028	0.038
D	0.81	1.07	0.032	0.042

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SNM3434S	SOT-23	3000PCS	7"

Headquarters

No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline

400-021-5756

Web

<https://www.semiware.com>

Sales Center

Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

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